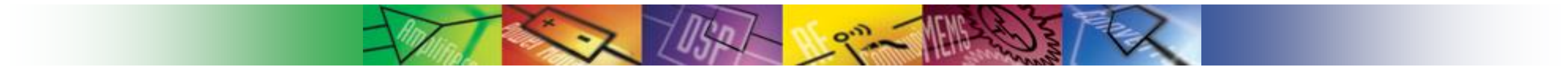

Product / Package Information

Package	LFCSP
Body Size (mm)	7 X 7 X .75 (2.8 EP)
Lead Count	12
Terminal Finish	100 Sn
MS Number	MS013005A

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	6.53E-02	93.7	937000	62.58	625771
Thermosets	Epoxy Resin	Proprietary	2.09E-03	3.0	30000	2.00	20035
Thermosets	Phenol Resin	Proprietary	2.09E-03	3.0	30000	2.00	20035
Other inorganic materials	Carbon Black	1333-86-4	2.09E-04	0.3	3000	0.20	2004
Subtotal			6.97 E-02	100.00	1000000	66.78	667846

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.86 E-02	97.50	975000	27.41	274120
Copper & its alloys	Iron	7439-89-6	6.89 E-04	2.35	23500	0.66	6607
Copper & its alloys	Zinc	7440-66-6	3.52 E-05	0.12	1200	0.03	337
Copper & its alloys	Phosphorus	7723-14-0	8.80 E-06	0.03	300	0.01	84
Subtotal			2.93 E-02	100.00	1000000	28.11	281148

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.87 E-04	100.0	1000000	0.28	2751

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.83 E-04	100.0	1000000	0.46	4632

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.91 E-04	99.0	990000	0.18	1832
Precious metals	Palladium	7440-05-3	1.93 E-06	1.0	10000	0.00	19
Subtotal			1.93 E-04	100.0	1000000	0.19	1851

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon	7440-21-3	3.70 E-03	100.0	1000000	3.54	35418

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.11 E-04	77.00	770000	0.49	4893
Other organic materials	Acrylic resin	Proprietary	4.64 E-05	7.00	70000	0.04	445
Other organic materials	Acrylate	Proprietary	3.65 E-05	5.50	55000	0.03	349
Other organic materials	Polybutadiene derivative	Proprietary	2.98 E-05	4.50	45000	0.03	286
Other organic materials	Epoxy resin	Proprietary	1.66 E-05	2.50	25000	0.02	159
Other organic materials	Butadiene Copolymer	Proprietary	9.95 E-06	1.50	15000	0.010	95
Others	Additive	Proprietary	9.95 E-06	1.50	15000	0.010	95
Others	Peroxide	Proprietary	3.32 E-06	0.50	5000	0.003	32
Subtotal			6.63 E-04	100.00	1000000	0.64	6354

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.04 E-01**	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
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